

-30V Dual P-Channel Fast Switching MOSFETs

■ DESCRIPTION

The STP4953 is the Dual P-Channel logic enhancement mode power field effect transistor is produced using high cell density advanced trench technology to provide excellent $R_{DS(ON)}$. This device is suitable for use as a load switch or in PWM and gate charge for most of the synchronous buck converter applications.

STP4953M-TRG ROHS Compliant This is Halogen Free

■ FEATURE

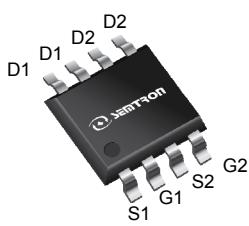
- ◆ -30V/-5.6A, $R_{DS(ON)} = 40m\Omega$ (typ.)@ $V_{GS} = -10V$
- ◆ -30V/-4.3A, $R_{DS(ON)} = 60m\Omega$ (typ.)@ $V_{GS} = -4.5V$
- ◆ Super high density cell design for extremely low $R_{DS(ON)}$
- ◆ Exceptional on-resistance and Maximum DC current capability

■ APPLICATIONS

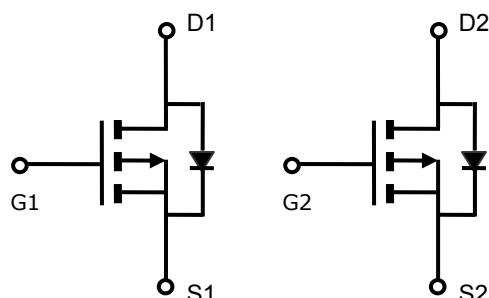
- ◆ Power Management in Note book
- ◆ Portable Equipment
- ◆ DSC
- ◆ LCD Display inverter
- ◆ Battery Powered System
- ◆ DC/DC Converter
- ◆ Load Switch



■ PIN CONFIGURATION



SOP-8
Top View



Dual P-Channel Fast Switching MOSFETs

■ PART NUMBER INFORMATION

<u>ST</u> <u>P</u> <u>4953</u> <u>M</u> - <u>TR</u> <u>G</u> a b c d e f	a : Company name. b : Channel type. c : Product Serial number. d : Package Code e : Handling Code f : Lead Plating Code G : Lead-free product This product is Halogen Free
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■ ORDERING INFORMATION

Part Number	Package Code	Handling Code	Shipping
STP4953M-TRG	M : SOP-8	TR : Tape&Reel	2.5K/Reel

※ Year Code : 00 ~ 90, 2010 : 00

※ Week Code : 01 ~ 54

※ SOP-8 : Only available in tape and reel packaging.

■ ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

Symbol	Parameter	Typical	Unit
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current, $V_{GS}=10\text{V}^A$	$T_A=25^\circ\text{C}$	-5.6
		$T_A=70^\circ\text{C}$	-4.0
I_{DM}	Pulsed Drain Current ^B	-20	A
E_{AS}	Single Pulse Avalanche energy $L=0.1\text{mH}^C$	59	mJ
I_{AS}	Avalanche Current	19	A
P_D	Power Dissipation	$T_A=25^\circ\text{C}$	2.0
		$T_A=70^\circ\text{C}$	1.4
T_J	Operation Junction Temperature	-55/150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55/150	$^\circ\text{C}$

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

■ THERMAL DATA

Symbol	Parameter	Min	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient ^A Steady-State			85	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Lead ^A Steady-State			60	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS($T_A = 25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Parameters						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-30			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.0		-2.0	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±20V			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-24V, V _{GS} =0V T _J =25°C			-1	μA
		V _{DS} =-24V, V _{GS} =0V T _J =55°C			-5	
R _{D(on)}	Drain-source On-Resistance ^B	V _{GS} =-10V, I _D =-5.6A V _{GS} =-4.5V, I _D =-4.3A	40 60	48 78		mΩ
G _f	Forward Transconductance	V _{DS} =-10V, I _D =-5.6A		6		S
Source-Drain Diode						
V _{SD}	Diode Forward Voltage ^B	I _S =-2.0A, V _{GS} =0V		-0.7	-1.2	V
I _S	Continuous Source Current ^{AD}				-6	A
Dynamic Parameters						
Q _g (-4.5V)	Total Gate Charge			6.3		nC
Q _{gs}	Gate-Source Charge	V _{DS} =-20V, V _{GS} =-4.5V I _D =-5.6A		2.7		
Q _{gd}	Gate-Drain Charge			3.1		
C _{iss}	Input Capacitance			625		pF
C _{oss}	Output Capacitance	V _{DS} =-25V, V _{GS} =0V f=1MHz		270		
C _{rss}	Reverse Transfer Capacitance			103		
t _{d(on)}	Turn-On Time			9		nS
t _r		V _{DD} =-12V, V _{GEN} =-10V, I _D =-5.0A, R _G =3.3Ω,		16.6		
t _{d(off)}	Turn-Off Time			21.8		
t _f				21		

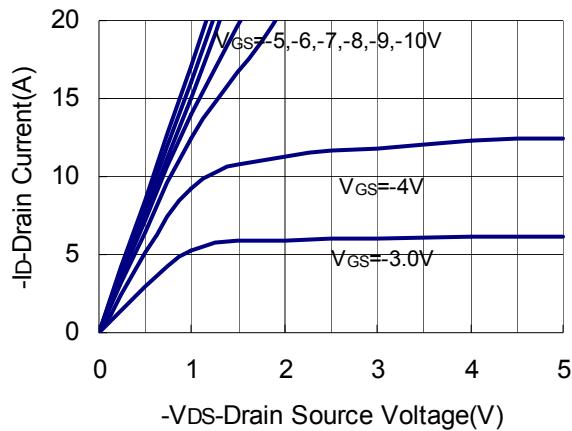
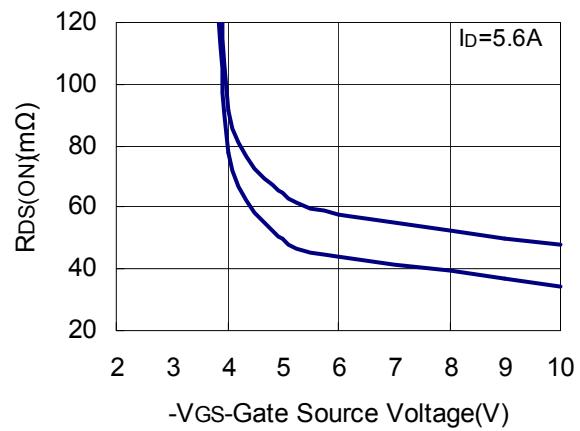
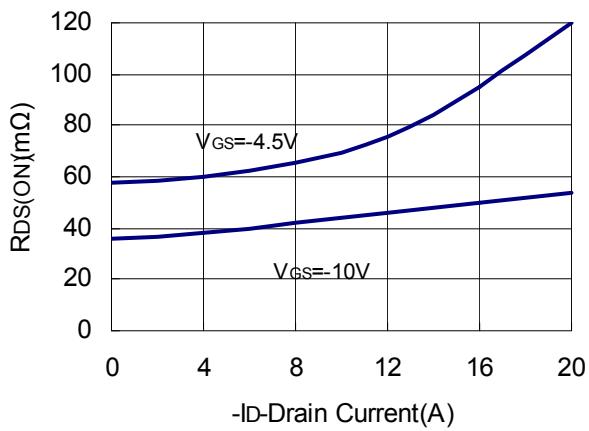
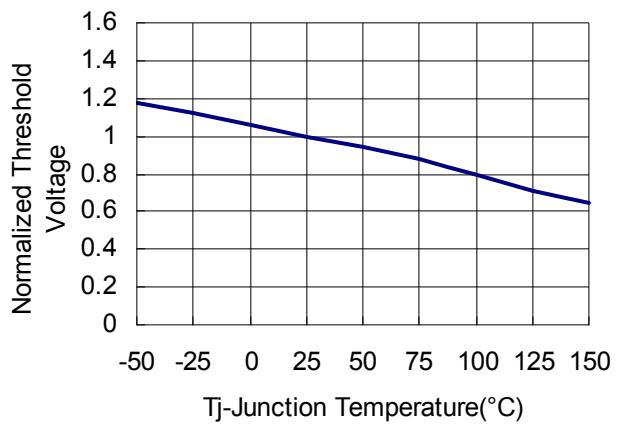
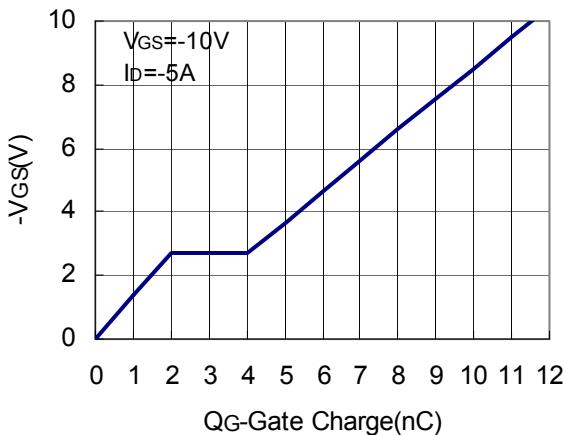
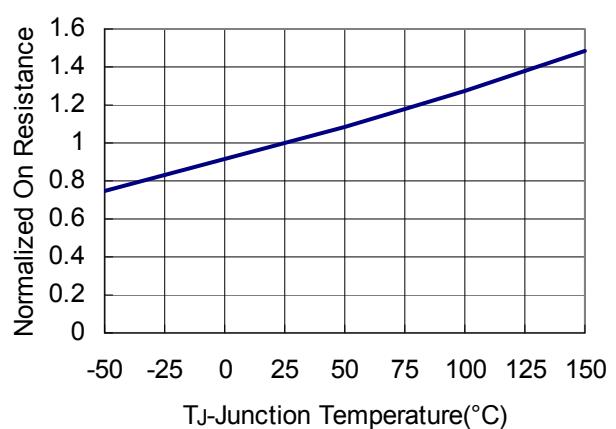
Note:

- A. The value of R_{θJA} is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C.
- B. The data tested by pulsed , pulse width ≤ 300μS , duty cycle ≤ 2%
- C. The EAS data shows Max. rating . The test condition is V_{DD}=-25V,V_{GS}=-10V,L=0.1mH.
- D. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

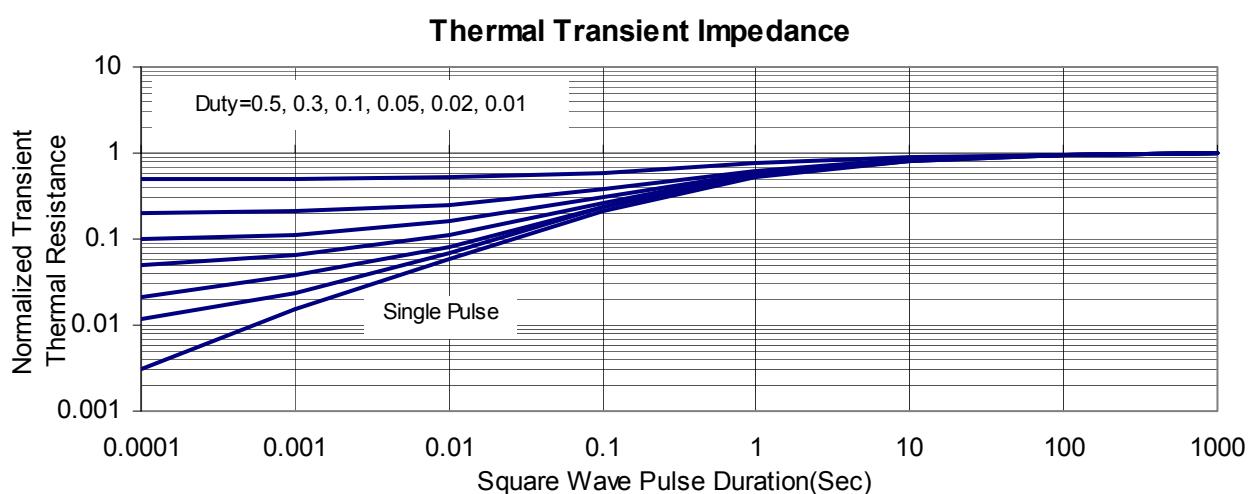
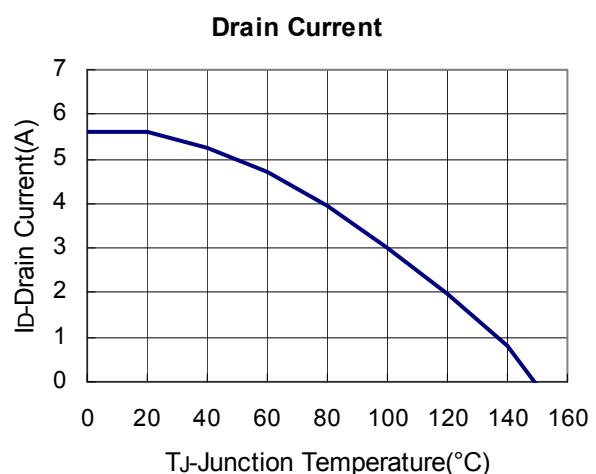
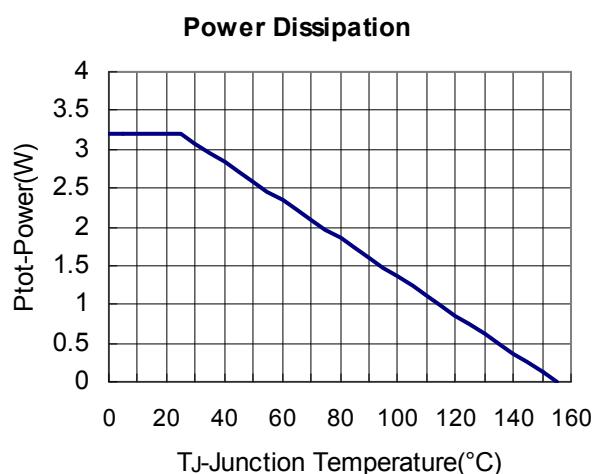
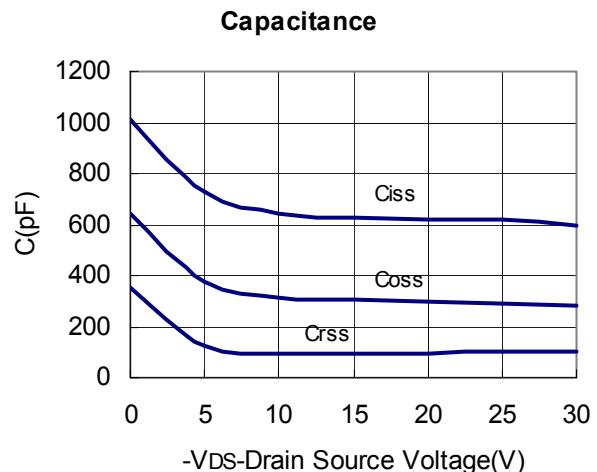
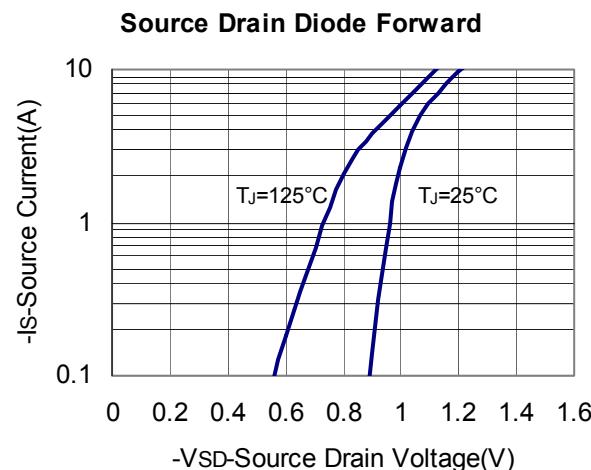
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TYPICAL CHARACTERISTICS

Output Characteristics

Drain-Source On Resistance

Drain Source On Resistance

Gate Threshold Voltage

Gate Charge

Drain Source On Resistance


■ TYPICAL CHARACTERISTICS



SOP-8 PACKAGE DIMENSIONS

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.040	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

